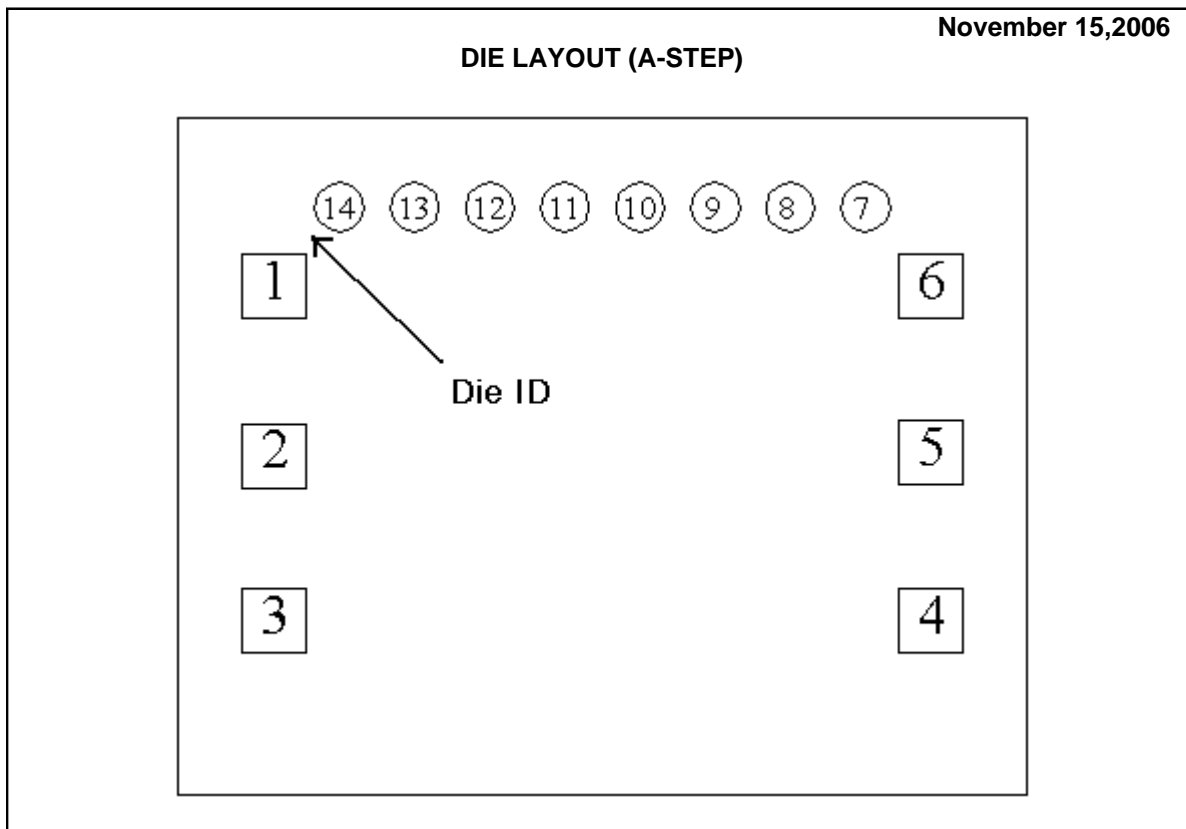


LM27-2PL MDA MCD2420A
±3°C ACCURATE, 145°C FACTORY PRESET THERMOSTAT WITH ACTIVE HIGH, PUSH/PULL
OVERTEMPERATURE SHUTDOWN OUTPUT



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM27A	Bond Pad Opening Size (min)	85µm x 85µm
Die Step	A	Bond Pad Metalization	Al_0.5%Cu
Physical Attributes		Passivation	PECVDXO+NITRIDE
Wafer Diameter	200mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1130µm x 902µm 44.5mils x 35.5mils	Back Side Connection	GND
Thickness	254µm Nominal		
Min Pitch	100µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in μm) **NC** = No Connection, **N.U.** = Not Used

SIGNAL NAME	PAD# NUMBER	XY COORDINATES		PAD SIZE	
		X	Y	X	Y
HYST	1	-437	225	85	x 85
OS	2	-437	0	85	x 85
NC	3	-437	-220	85	x 85
V+	4	437	-220	85	x 85
GND	5	437	5	85	x 85
V _{TEMP}	6	437	225	85	x 85
NC	7	350	331	65	x 65
NC	8	250	331	65	x 65
NC	9	150	331	65	x 65
NC	10	50	331	65	x 65
NC	11	-50	331	65	x 65
NC	12	-150	331	65	x 65
NC	13	-250	331	65	x 65
NC	14	-350	331	65	x 65

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